



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET

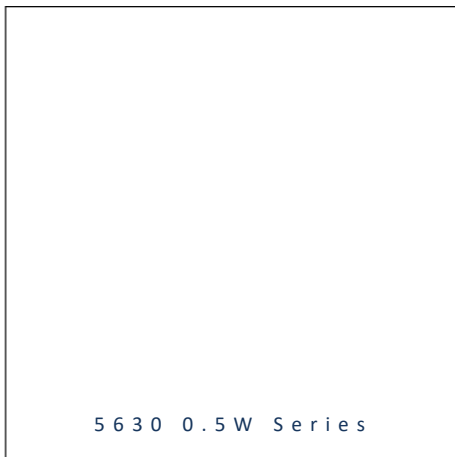


- ▶ PLCC4 SMD
- ▶ 5630 0.5W Series
- ▶ Yellow (590nm)

NOY18S74



Release Date: 19 May 2017 Version: A1.0



5630 0.5W Series

5630 0.5W Series

RoHS
Compliant



FEATURES:

- **Package:** PLCC4 High Top View SMT Package
- **Forward Current:** 150mA
- **Forward Voltage (typ.):** 2.4V
- **Luminous Flux (typ.):** 6500mcd@150mA
- **Colour:** Yellow
- **Wavelength:** 590nm
- **Viewing angle:** 120°
- **Materials:**
 - Die: AlGaInP
 - Resin: Silicon (Water Clear)
 - L/T Finish: Ag plated
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - Dominant wavelength
- **Soldering methods:** IR Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 12mm tape with 2000/reel, ø180mm (7'')

APPLICATIONS:

- Decorative Lighting
- Backlighting
- Indicator
- Outdoor Lighting
- Garden Light

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	150	mA
Peak Forward Current (Duty 1/10; width 10KHz)	I _{FP}	300	mA
Reverse Current @5V	I _R	10	μA
Power Dissipation	P _D	0.45	W
Electrostatic Discharge	ESD	2000	V
Junction Temperature	T _J	125	°C
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C
Soldering Temperature	T _{SD}	260	°C

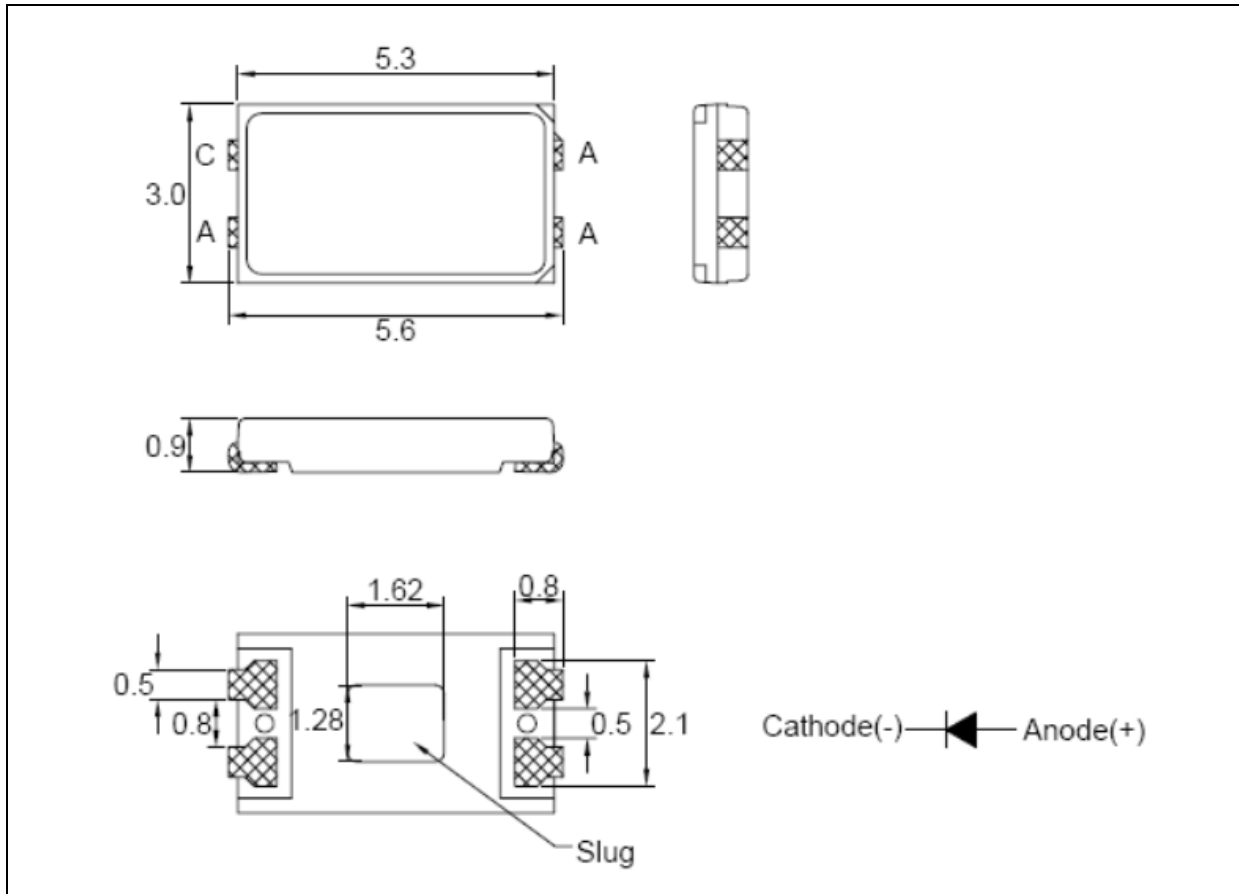
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	2.0	---	3.0	V	I _F =150mA
Luminous Intensity	I _V	4000	6500	---	mcd	I _F =150mA
Dominant Wavelength	λ _D	---	590	---	nm	I _F =150mA
Spectral Half Width	Δλ	---	20	---	nm	I _F =150mA
Viewing Angle	2θ _{1/2}	---	120	---	deg	I _F =150mA

- Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2θ_{1/2}) ±5%

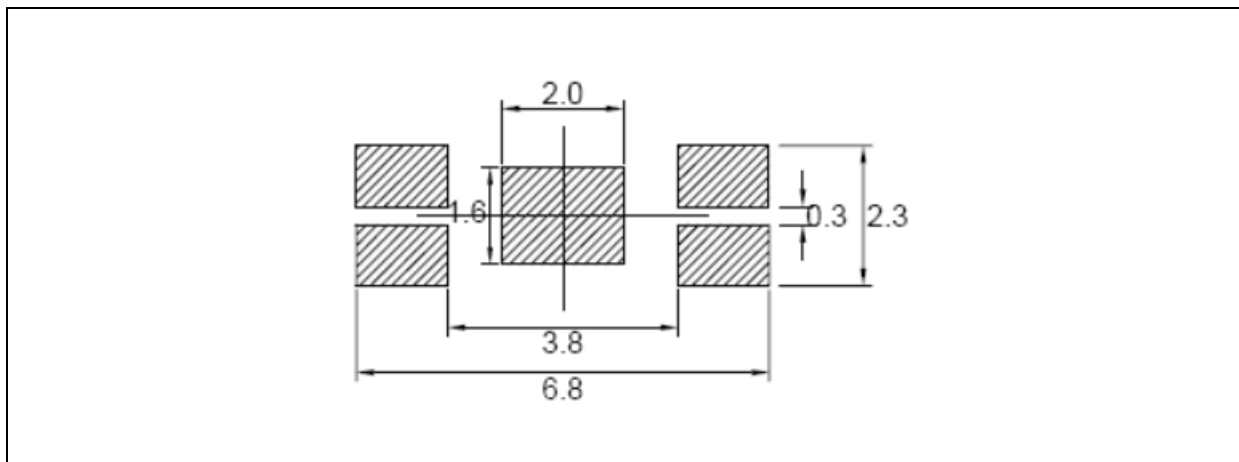
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 150\text{mA}$):

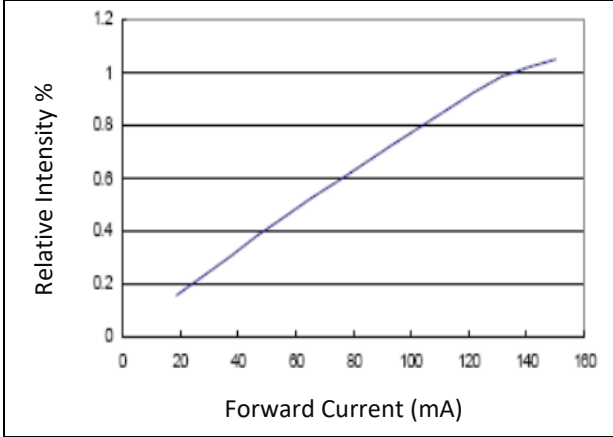
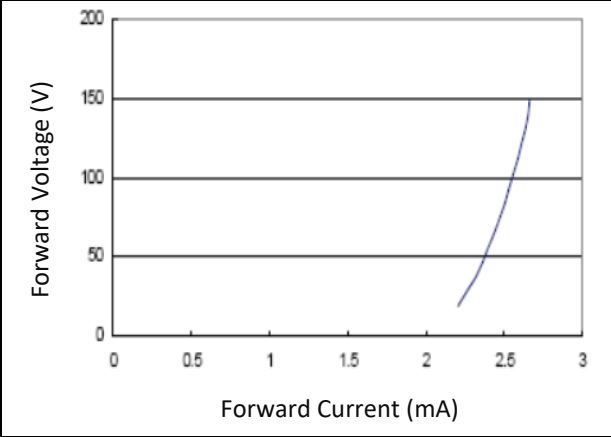
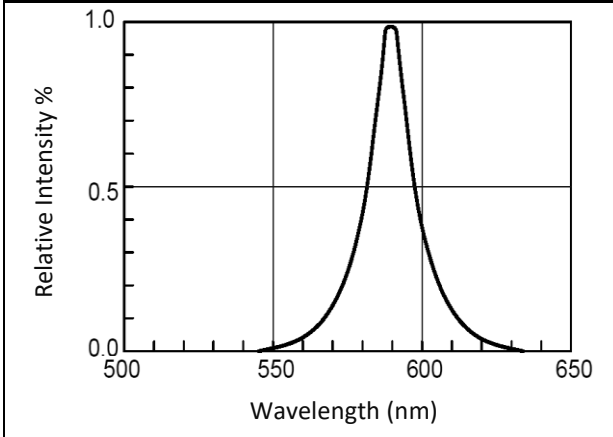
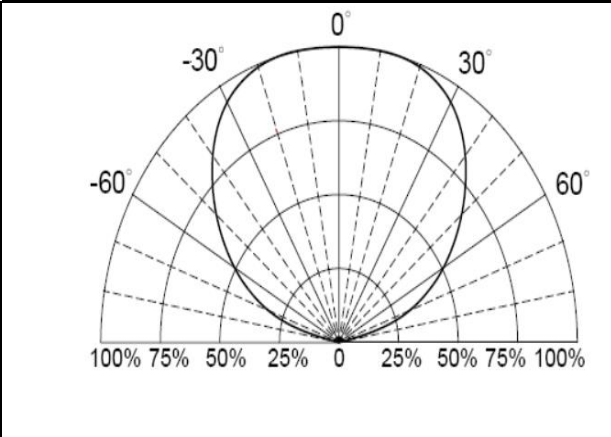
Code	Min.	Max.	Unit
V	2.0	3.0	V

 Luminous Intensity Classifications ($I_F = 150\text{mA}$):

Code	Min.	Max.	Unit
Y-2	4000	5000	mcd
Z-1	5000	6500	
Z-2	6500	8000	
AA-1	8000	10000	
AA-2	10000	12500	

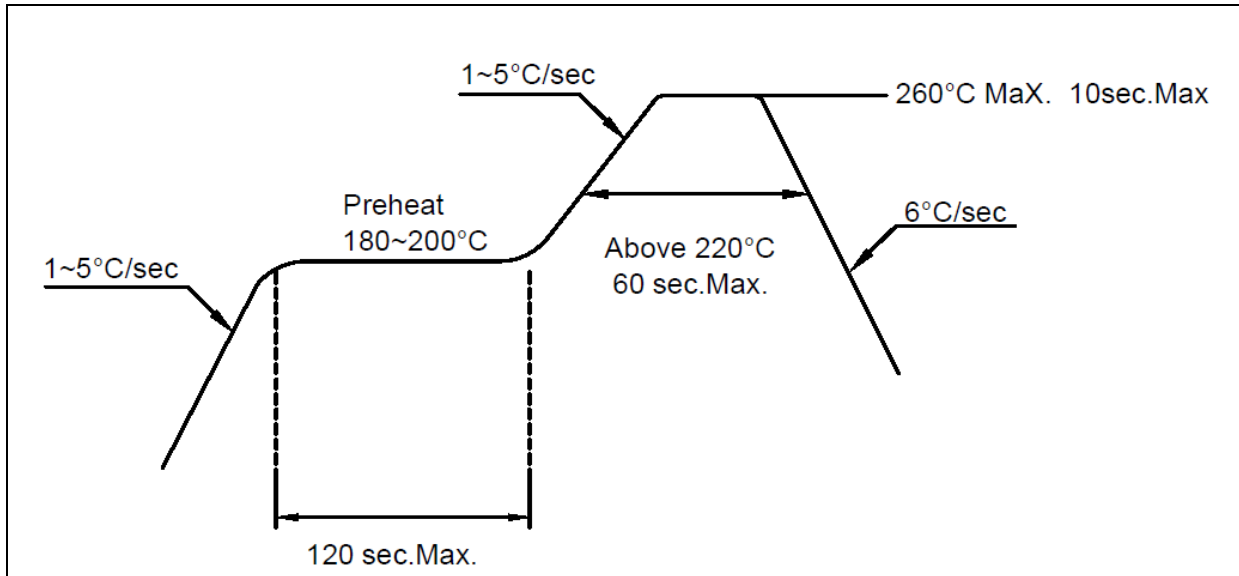
 Dominant Wavelength Classifications ($I_F = 150\text{mA}$):

Code	Min.	Max.	Unit
15	585	587	nm
16	587	589	
17-1	589	590	
17-2	590	591	
17-3	591	592	
18	592	595	

ELECTRO-OPTICAL CHARACTERISTICS:
Relative Intensity v.s. Forward Current

Forward Voltage v.s. Forward Current

Relative Intensity v.s. Wavelength

Directive Radiation


RECOMMENDED SOLDERING PROFILE:

IR Reflow Lead-free Solder:

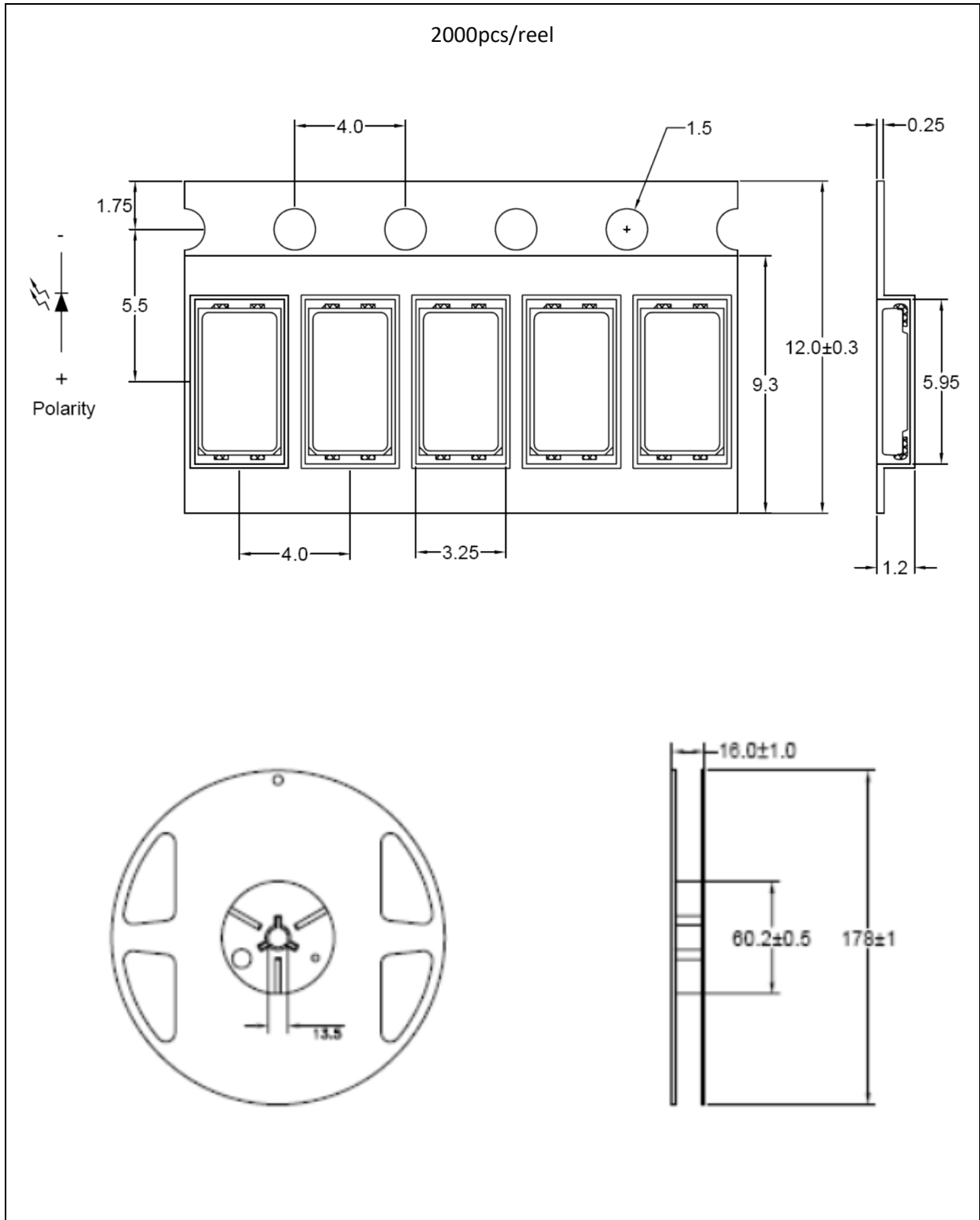


Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.
3. Recommended reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

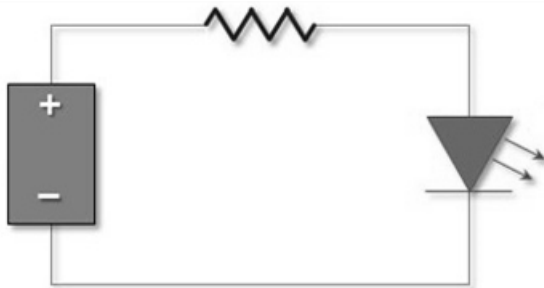
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 15hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	19/05/2017	Datasheet set-up.